

# MOSFET

#### **Product Summary**

V(BR)DSS	RDS(on)MAX	lo
-20V	110mΩ@-4.5V	-2.3A
-200	140mΩ@-2.5V	-2.3A

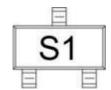
#### Feature

- TrenchFET Power MOSFET
- Excellent R<sub>DS(on)</sub> and Low Gate Charge

### Application

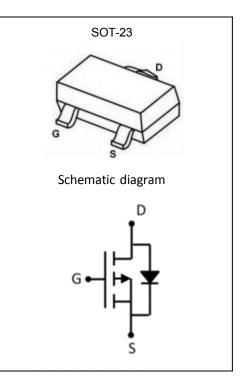
- DC/DC Converter
- Load Switch for Portable Devices
- Battery Switch

#### MARKING:



#### ABSOLUTE MAXIMUM RATINGS (Ta=25°C unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	V
Gate-Source Voltage	Vgs	±8	V
Continuous Drain Current	lD	-2.3	A
Pulsed Drain Current (t=300µs)	I <sub>DM</sub>	-10	A
Power Dissipation	PD	0.35	W
Thermal Resistance from Junction to Ambient	Reja	357	°C <b>/W</b>
Junction Temperature	TJ	150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C



**RS2301E** 

20V P-Channel



# MOSFET ELECTRICAL CHARACTERISTICS(Ta=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Туре	Max	Unit
Static Characteristics				•	•	
Drain-source breakdown voltage	V(BR)DSS	V <sub>GS</sub> = 0V, I <sub>D</sub> =-250µA	-20			V
Zero gate voltage drain current	I <sub>DSS</sub>	$V_{DS}$ =-20V, $V_{GS}$ = 0V			-1	μA
Gate-body leakage current	lgss	V <sub>GS</sub> =±8V, V <sub>DS</sub> = 0V			±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250µA	-0.4	-0.7	-1	V
		Vgs =-4.5V, Id =-3A		70	110	
Drain-source on-resistance <sup>a</sup>	R <sub>DS(on)</sub>	Vgs =-2.5V, ID =-2A		110	140	mΩ
Forward tranconductance <sup>a</sup>	<b>g</b> FS	VDS =-5V, ID =-2A	5			S
Dynamic characteristics <sup>b</sup>			·			
Input Capacitance	Ciss			405		
Output Capacitance	Coss	V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V,f =1MHz		75		pF
Reverse Transfer Capacitance	Crss	-		55		
Gate resistance	Rg	f =1MHz		6		Ω
Total Gate Charge	Qg			3.3	12	
Gate-Source Charge	Qgs	VDS =-10V,VGS =-2.5V,ID=-3A		0.7		nC
Gate-Drain Charge	Qgd	-		1.3		
Turn-on delay time	t <sub>d(on)</sub>			11		
Turn-on rise time	tr	VDD=-10V,VGEN=-4.5V,ID=-1A		35		
Turn-off delay time	td(off)	$R_{L}=10\Omega, R_{GEN}=1\Omega$		30		ns
Turn-off fall time	tr			10		
Source-Drain Diode characteristics	; ;					
Diode forward current	ls	Tc=25℃			-2.3	А
Diode pulsed forward current <sup>a</sup>	Іѕм				-10	А
Diode Forward voltage	V <sub>DS</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =-1.3A			-1.2	V

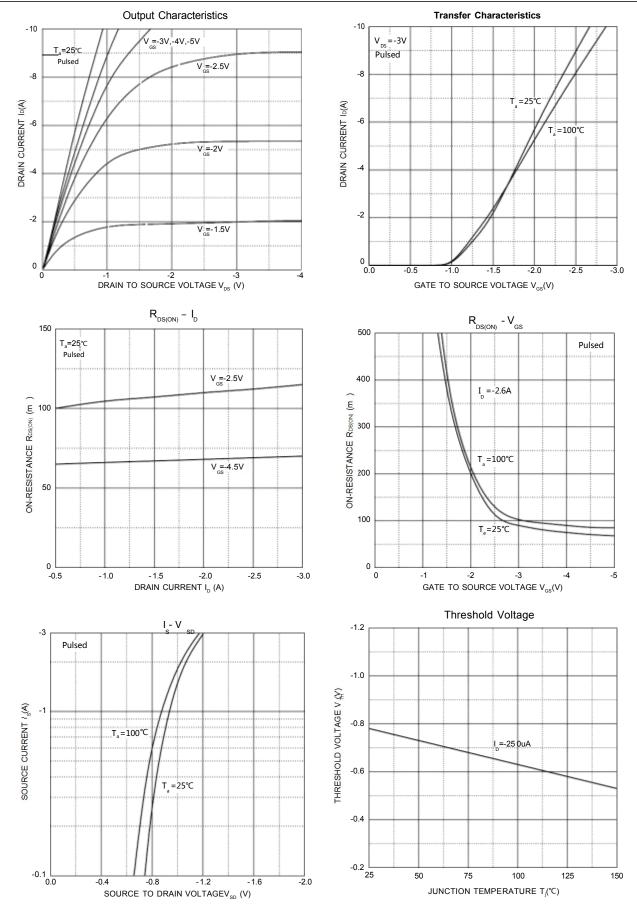
Notes :

a.Pulse Test : Pulse Width < 300µs, Duty Cycle ≤2%.

b.Guaranteed by design, not subject to production testing.

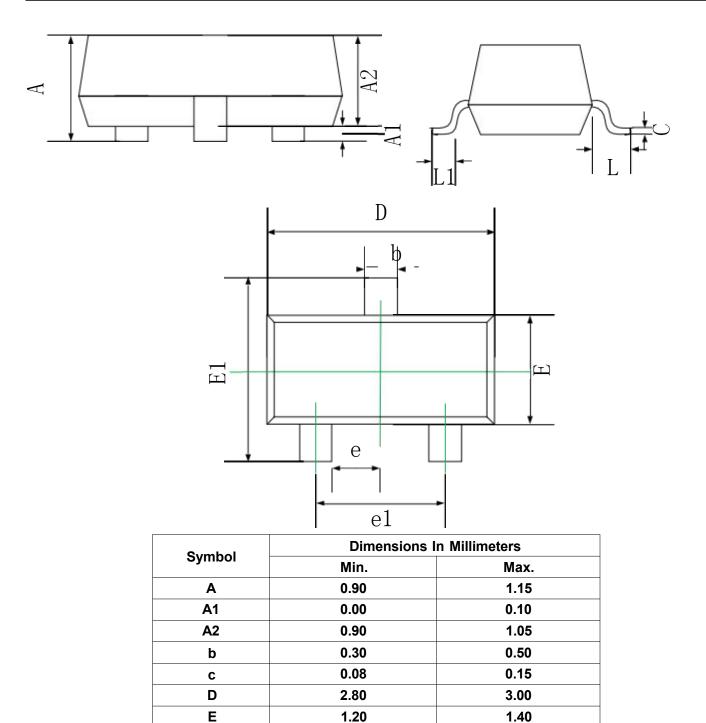


#### **Typical Electrical and Thermal Characteristics**





## SOT-23 Package Information



2.25

1.80

0.30

2.55

2.00

0.50

0.95 REF.

0.55 REF.

E1

е

e1

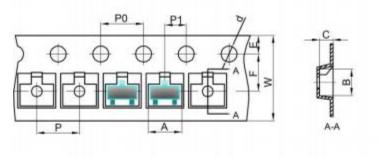
L L1



SOT-23 Tape and Reel

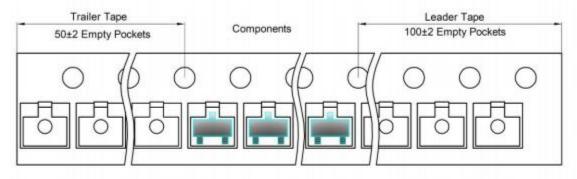
# SOT-23 Tape and reel

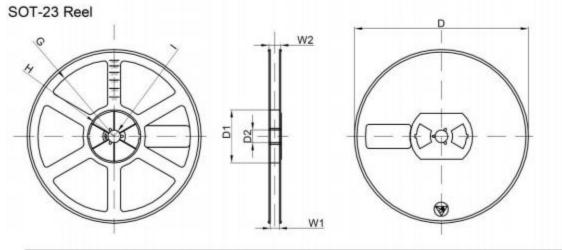
SOT-23 Embossed Carrier Tape



Dimensions are in millimeter										
Pkg type	A	В	С	d	E	F	P0	Р	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

## SOT-23 Tape Leader and Trailer





			Dimensio	ons are in millime	ter			
Reel Option	D	D1	D2	G	н	E	W1	W2
7°Dia	Ø178.00	54.40	13.00	R78.00	R25.60	R6.50	9.50	12.30

REEL	Reel Size	Box	Box Size(mm)	Carton	Carton Size(mm)	G.W.(kg)
3000 pcs	7 inch	30,000 pcs	203×203×195	120,000 pcs	438×438×220	

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